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Docket No. 99,952

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### CLAIMS

Claim 1. (currently amended) A continuous process of providing a highly smooth surface to a metallic tape, the process comprising:

passing a metallic tape that is a polycrystalline metal including nickel having an initial roughness of more than about 10 nm as a RMS roughness through an acid bath contained within a polishing section of an electropolishing unit over a pre-selected period of time; and,

passing a mean surface current density of at least 0.18 amperes per square centimeter through the metallic tape during the period of time the metallic tape is in the acid bath whereby the roughness of the metallic tape is reduced to a RMS roughness of less than about 4 nm.

Claim 2. (cancelled)

Claim 3. (previously amended) The process of claim 1 wherein the mean surface current density is at least 0.37 amperes per square centimeter and the RMS roughness of the metallic tape is reduced to less than 0.5 nm.

Claim 4. (original) The process of claim 1 wherein the RMS roughness of the metallic tape is reduced to less than 0.5 nm.

Claim 5. (original) The process of claim 1 wherein the acid bath includes a mixture of sulphuric acid and phosphoric acid.

Claim 6. (cancelled)

Claim 7. (cancelled)

Claim 8. (cancelled)

Claim 9. (original) The process of claim 1 wherein the metallic tape is in direct electrical contact with an anode in said electropolishing unit while said metallic tape is within an electrically conductive liquid throughout said electropolishing unit and within

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said acid bath in said polishing section, said acid bath further in contact with a cathode in said electropolishing unit so as to complete an electrical circuit.

Claim 10. (original) The process of claim 9 wherein the anode includes a metal selected from the group consisting of titanium, niobium, tantalum, platinum, rhenium, rhodium, nickel, chromium, gold and silver.

Claim 11. (original) The process of claim 10 wherein the acid bath includes a mixture of sulphuric acid and phosphoric acid.

Claim 12. (original) The process of claim 1 wherein the metallic tape is in direct electrical contact with an anode in said electropolishing unit while said metallic tape is in contact with mechanical contacts as the metallic tape is passed through the acid bath so as to complete an electrical circuit.

Claim 13. (original) The process of claim 1 wherein the metallic tape is passed through the acid bath and the acid bath provides electrical contact with the metallic tape.

Claim 14. (withdrawn) A template article comprising:

a metallic substrate characterized by a highly smooth RMS roughness level of less than about 4 nm, the highly smooth RMS roughness level provided through the process of claim 1;

one or more intermediate layers upon the surface of the metallic substrate; and,

a layer of an oriented cubic oxide material having a rock-salt-like structure upon the one or more intermediate layers.

Claim 15. (withdrawn) The template article of claim 14 wherein said metallic substrate characterized by a highly smooth RMS roughness level of less than about 1 nm.

Claim 16. (withdrawn) The template article of claim 14 wherein said one or more layers includes a layer of an inert oxide material upon the surface of the metallic substrate; and,

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a layer of an oxide or oxynitride material upon the inert oxide material layer.

Claim 17. (withdrawn) The template article of claim 15 wherein said one or more layers includes a layer of an inert oxide material upon the surface of the metallic substrate; and,

a layer of an oxide or oxynitride material upon the inert oxide material layer.

Claim 18. (withdrawn) The template article of claim 14 wherein said cubic oxide material is magnesium oxide.

Claim 19. (withdrawn) The template article of claim 14 wherein said magnesium oxide is deposited by ion-beam-assisted deposition.